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# Endcap Modules for the ATLAS SemiConductor Tracker

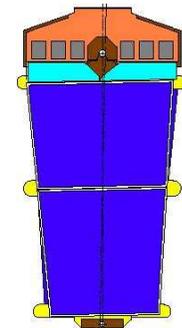


RD03, Firenze, September 29<sup>th</sup>, 2003

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(For the ATLAS-SCT Collaboration)

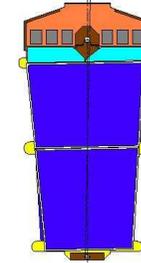




# The plan of this presentation

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Introduction

The forward modules



Mechanical performance



Electrical performance



Test beam results



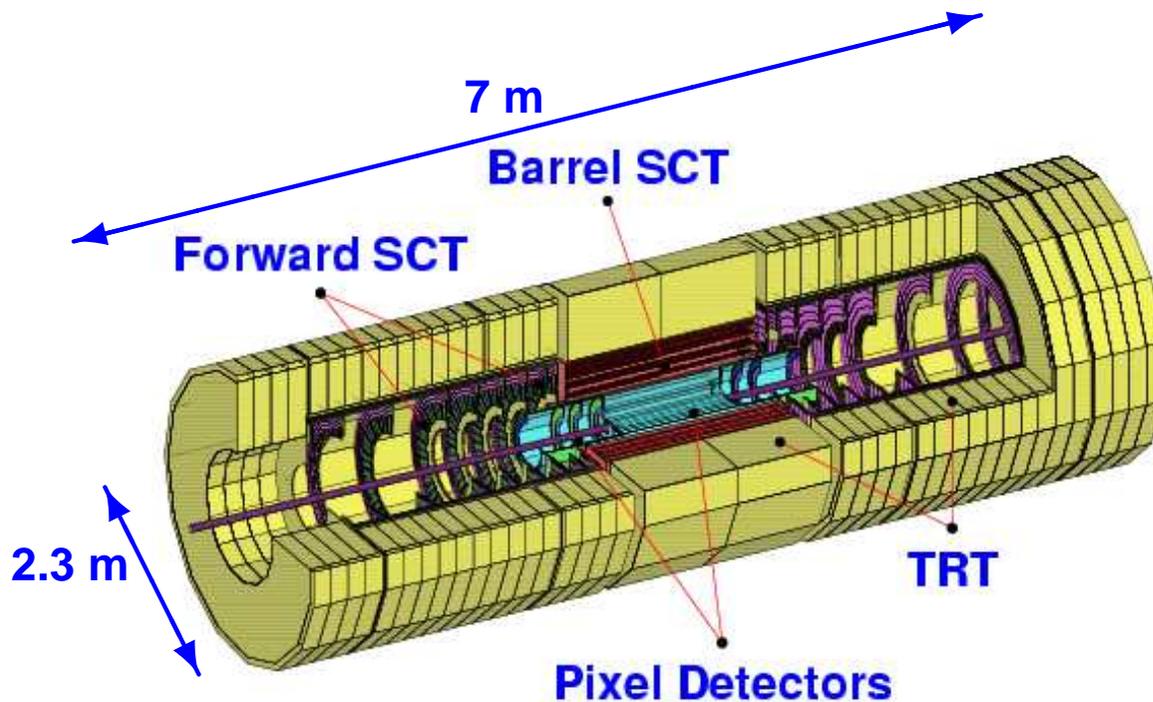
Status of module production



Conclusions and Outlook



# The ATLAS inner detector



**In this presentation, only the Semi Conductor Tracker will be discussed.**

## The Pixel Detector

- Radius 4.8 – 16 cm.
- 3 layers, 10 disks.
- $1.4 \cdot 10^8$  read-out channels.
- $\sigma$ :  $12 \mu m$  ( $R\Phi$ ) and  $\approx 70 \mu m$  ( $z/R$ ).

## The Semi Conductor Tracker

- Radius 27 – 52 cm.
- 4 layers, 18 disks
- $6.3 \cdot 10^6$  read-out channels.
- 4088 modules,  $61 \text{ m}^2$  silicon
- $\sigma$ :  $16 \mu m$  ( $R\Phi$ ) and  $580 \mu m$  ( $z/R$ ).

## The Transition Radiation Tracker

- Radius 56 – 107 cm.
- 100 k / 320 k straws in barrel / end cap.
- 420 k read-out channels.
- Xe radiator for electron-detection.
- $\sigma$ :  $170 \mu m$  / per straw.



# The SCT forward part - how to build a module

## Hybrid

A 6-layer copper-polyimid flex on a carbon substrate

## Fixations

Precision  $20 \mu m$

## Si-wafers

ca.  $6 \times 6 \times 0.285 \text{ cm}^3$   
768 single-sided p-type strips on n-type substrate with  $50\text{-}90 \mu m$  pitch

## Read-out chips

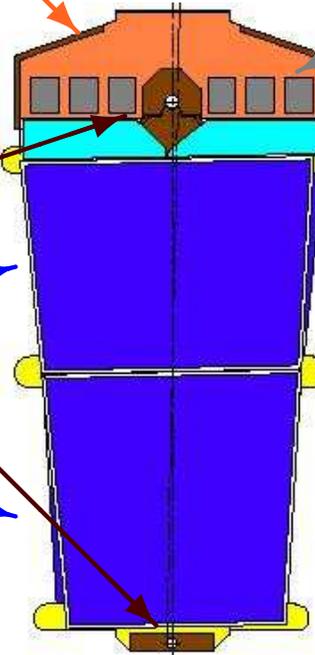
6 ABCD3T chips per side with binary read-out

## Fan-ins

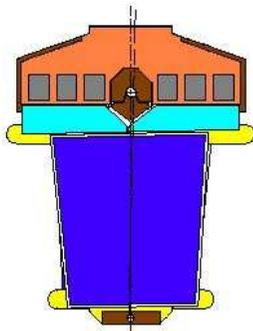
4/module, glass with Al-strips of  $300 \mu m$  thickness

## Support-structure (Spine)

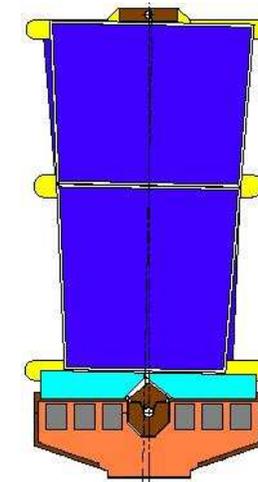
Thermal Pyrolytic Graphite thickness  $500 \mu m$ ,  $1700 \text{ W/m/K}$



Middle module



Inner module

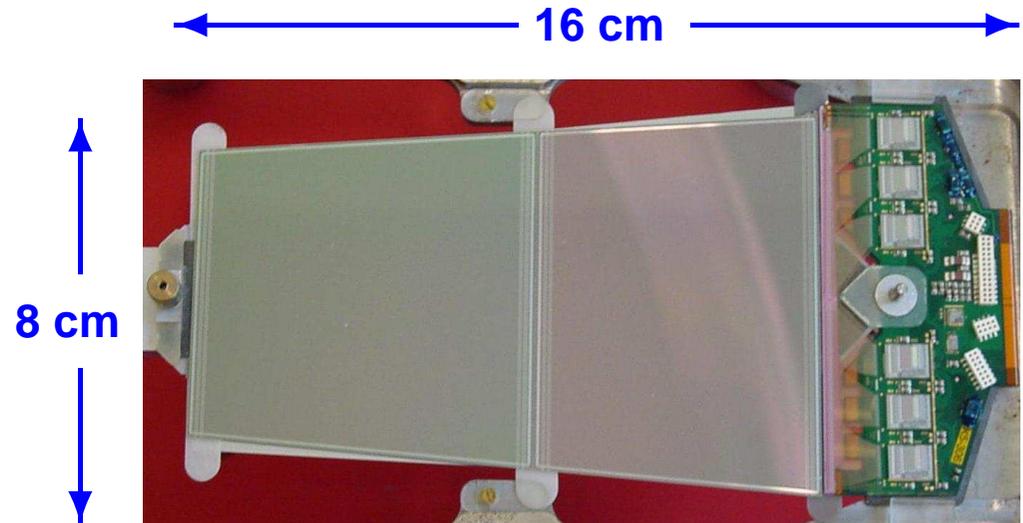


Outer module



## SCT forward modules - some design values

- Bias voltage:  $< 500$  V.
- Produced heat:  $< 7$  W per module.
- Gain: **50 mV/fC.**
- Linearity: **better than 5%.**
- Peaking time: 20 ns.
- Signal charge: 3.3 fC,  $S/N > 10$ .
- Noise:  **$< 1500(1900)$  e<sup>-</sup> ENC before (after) irradiation.**
- Noise occupancy:  **$< 5 \cdot 10^{-4}$ .**
- Hit efficiency:  **$> 99\%$ .**
- Time walk:  **$\leq 16$  ns, and bunch crossing resolution better than 99%.**
- $\sigma = 16(580)$   $\mu\text{m}$   $\perp$  ( $\parallel$ ) to the strips.
- Two-track resolution: 200  $\mu\text{m}$ .

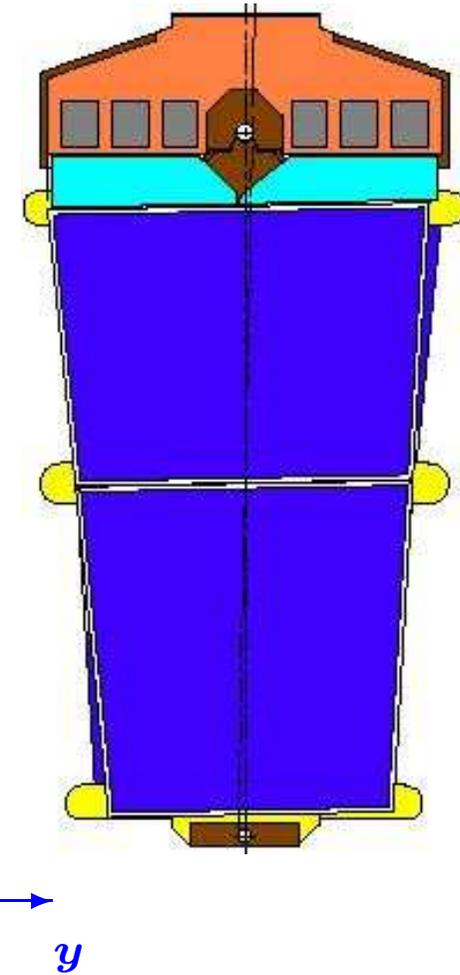
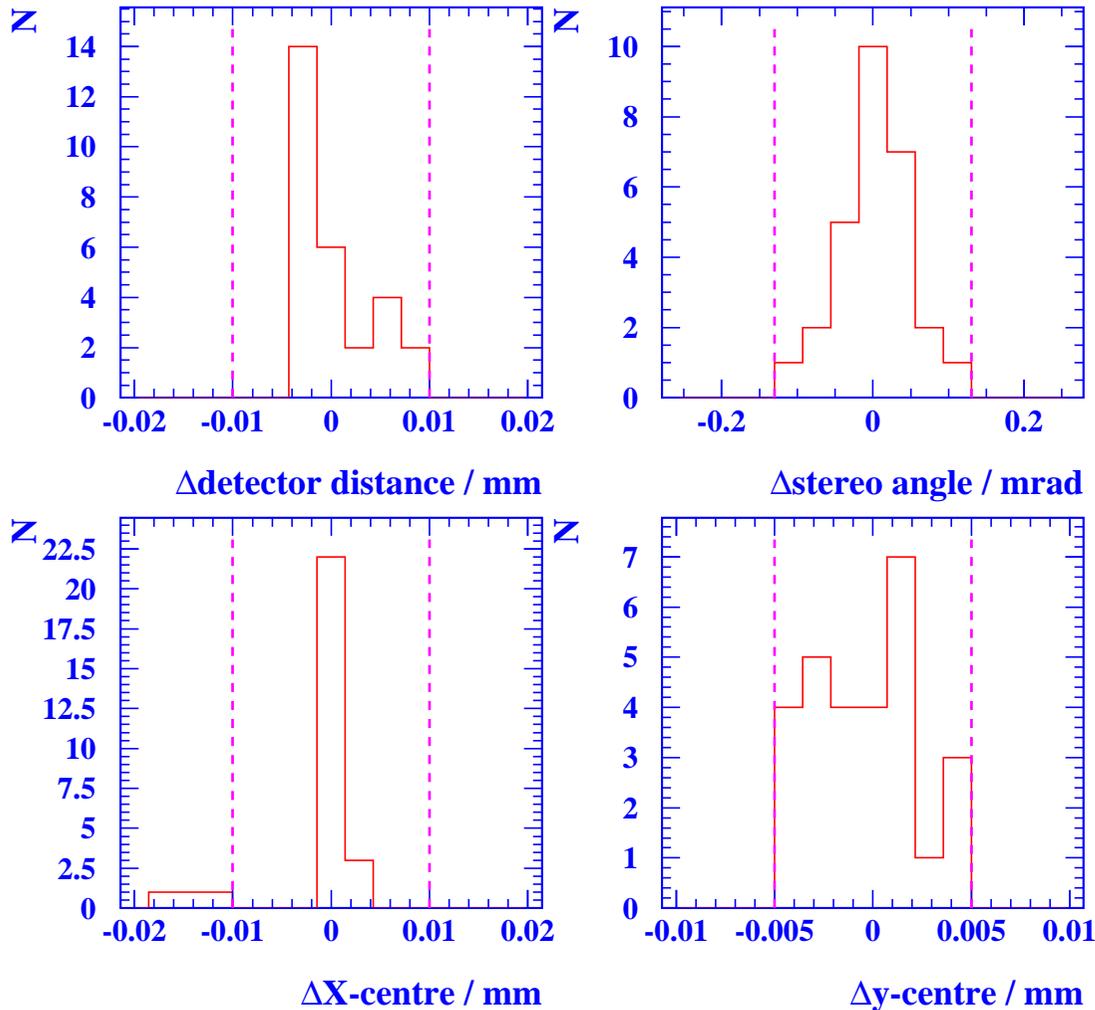


**The SCT modules are very delicate objects that have to be built with great care.**



# The mechanical reproducibility

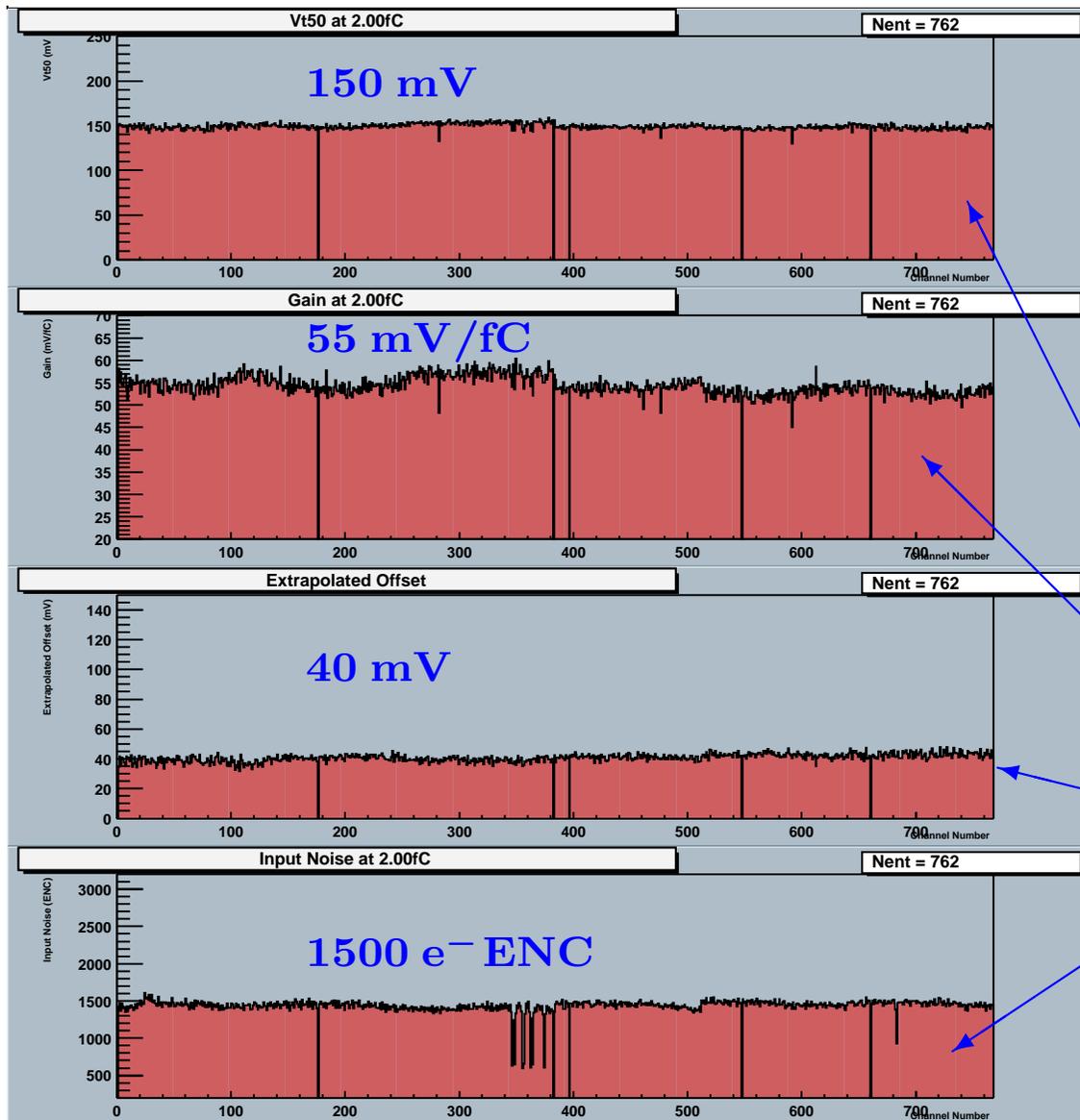
Results from 28 pre-series modules ( - - - tolerances )



**The modules can be built within specifications with high yield.**



# An example of the electrical performance



- Test of a non perfect hybrid (dead channels are visible as black lines). Shown are the results for one side of the hybrid ( $6 \times 128 = 768$  channels), tested at 2 fC injected charge.
- The results are obtained by analyzing the S-curves from threshold scans.

The output signal.

The calculated gain.

The extrapolated offset for 0 fC.

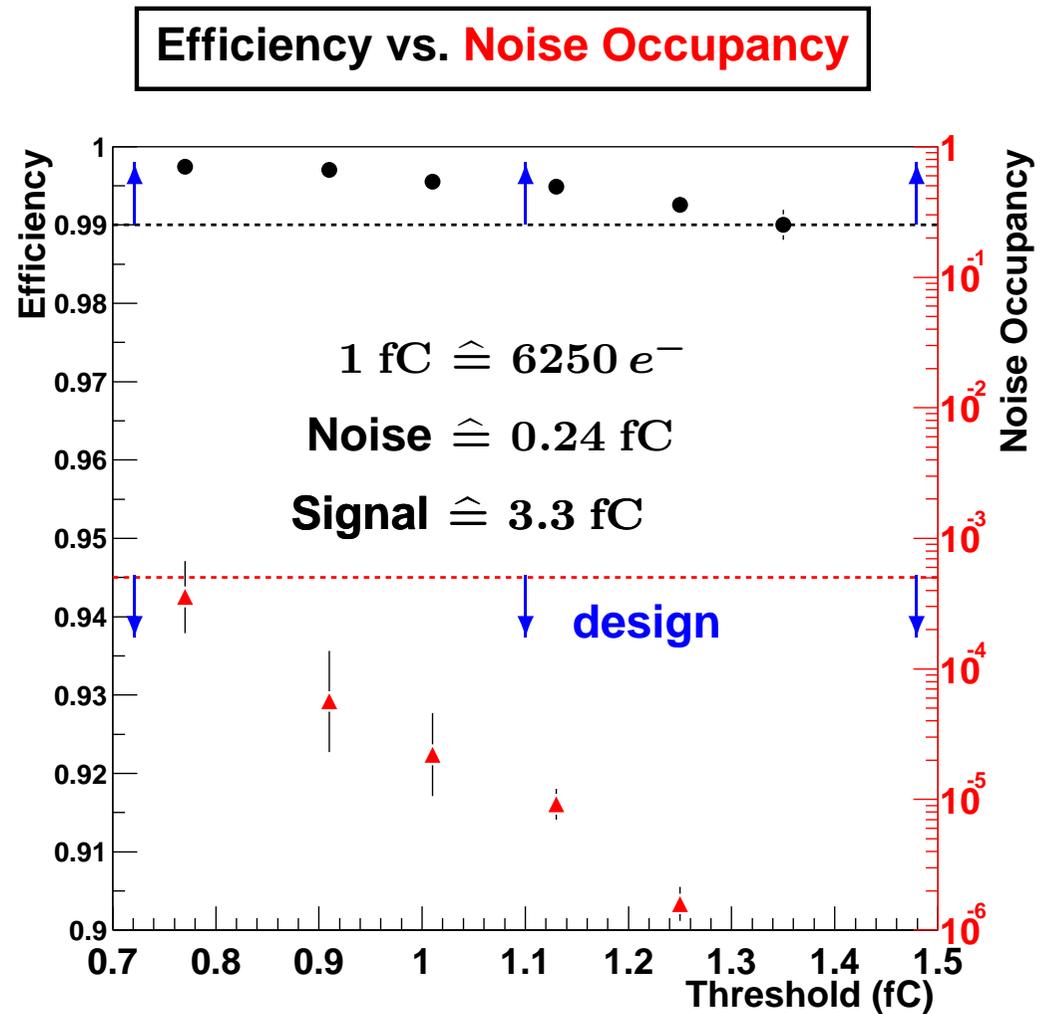
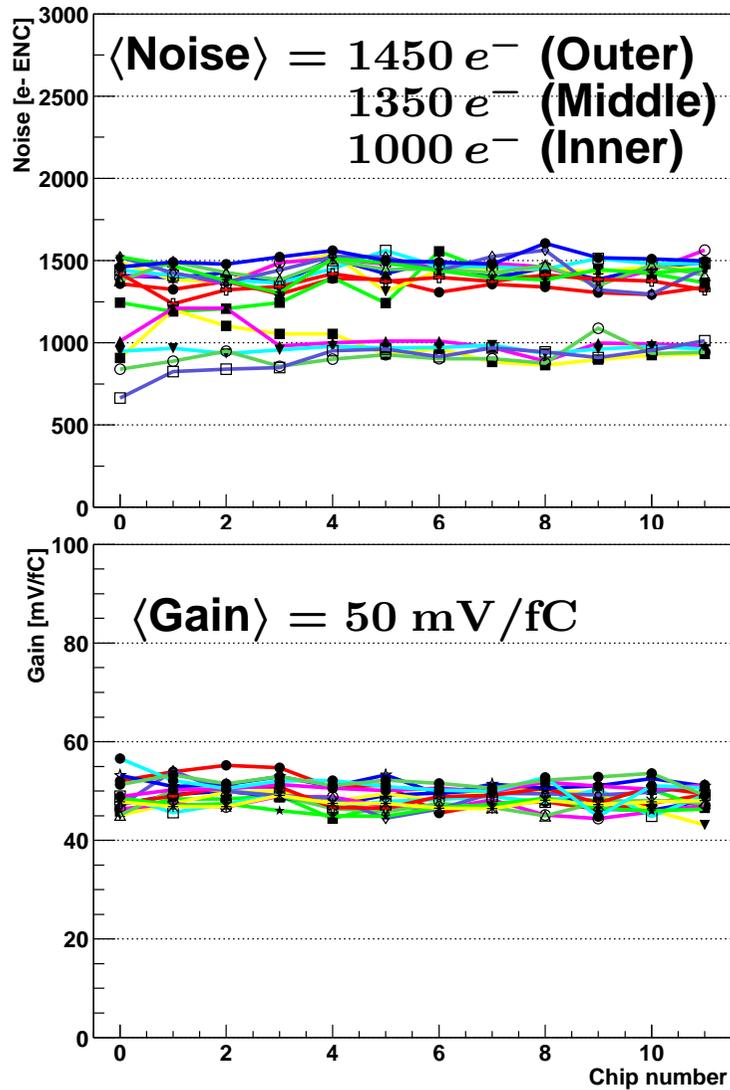
The noise in e<sup>-</sup> ENC.

The channel to channel variations within a module are small.

0 ... 768



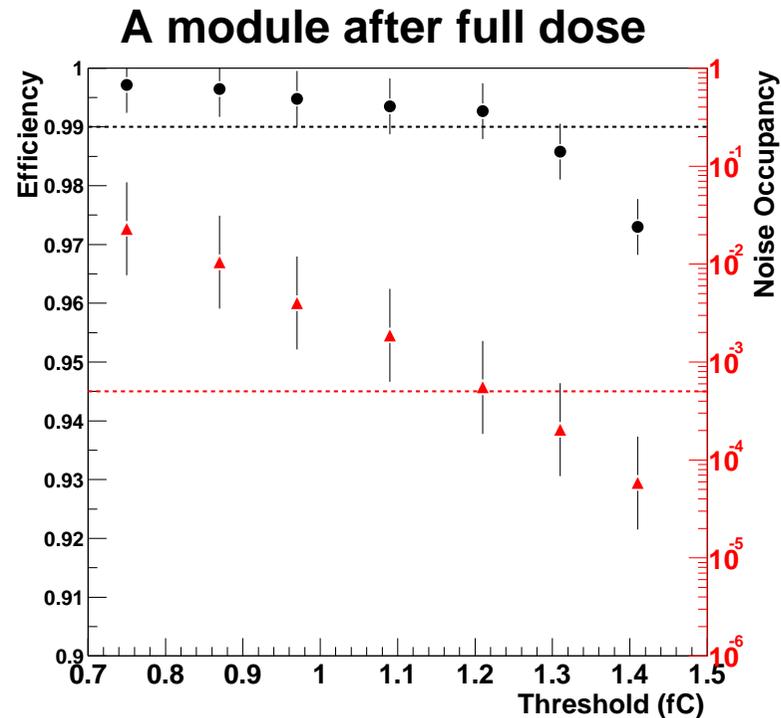
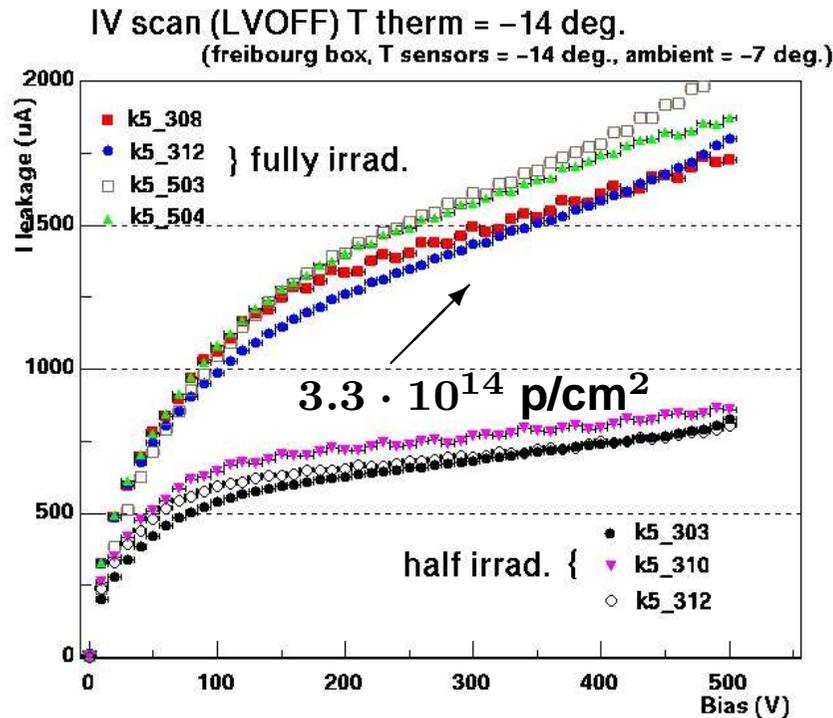
# Some properties of non-irradiated modules



**The non-irradiated modules are well within the design limits.**



# Performance degradation for irradiated modules

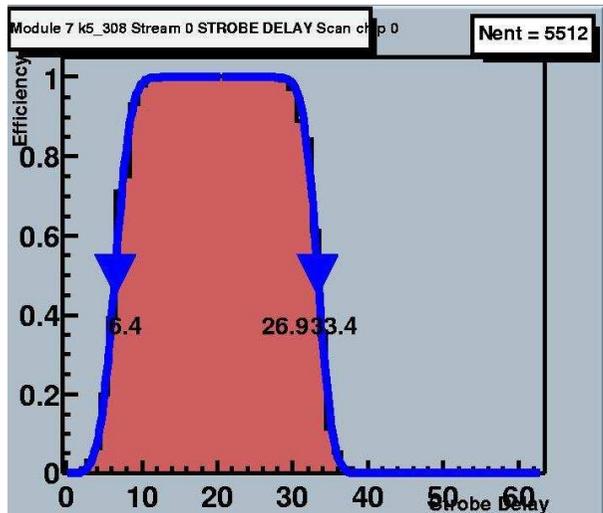


- Gain: 50 → 30 mV/fC ⇒ **Smaller signals.**
- Noise: 1500 → 2100 – 2400 e<sup>-</sup> ENC ⇒ **Worse S/N ratio.**
- Temperature dependence: 6 → 20 e<sup>-</sup> ENC/°C ⇒ **Higher temperature sensitivity.**
- Threshold spread: 160 → 600 e<sup>-</sup> ENC ⇒ **Increased noise.**

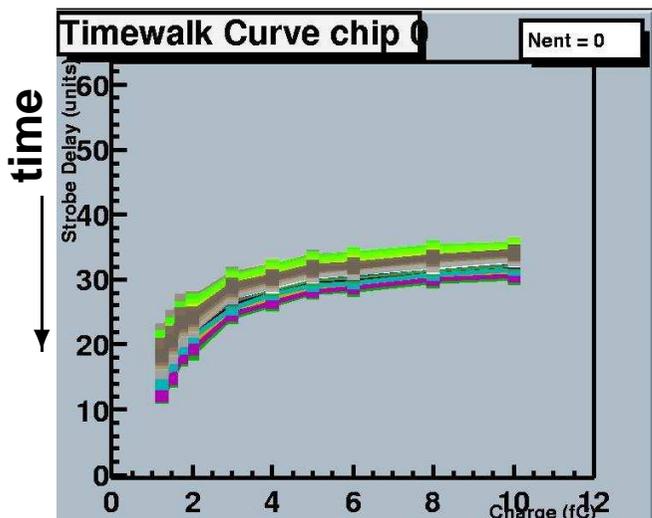
**The operation margin for irradiated modules is rather narrow.**



# Lets do the time walk



← time

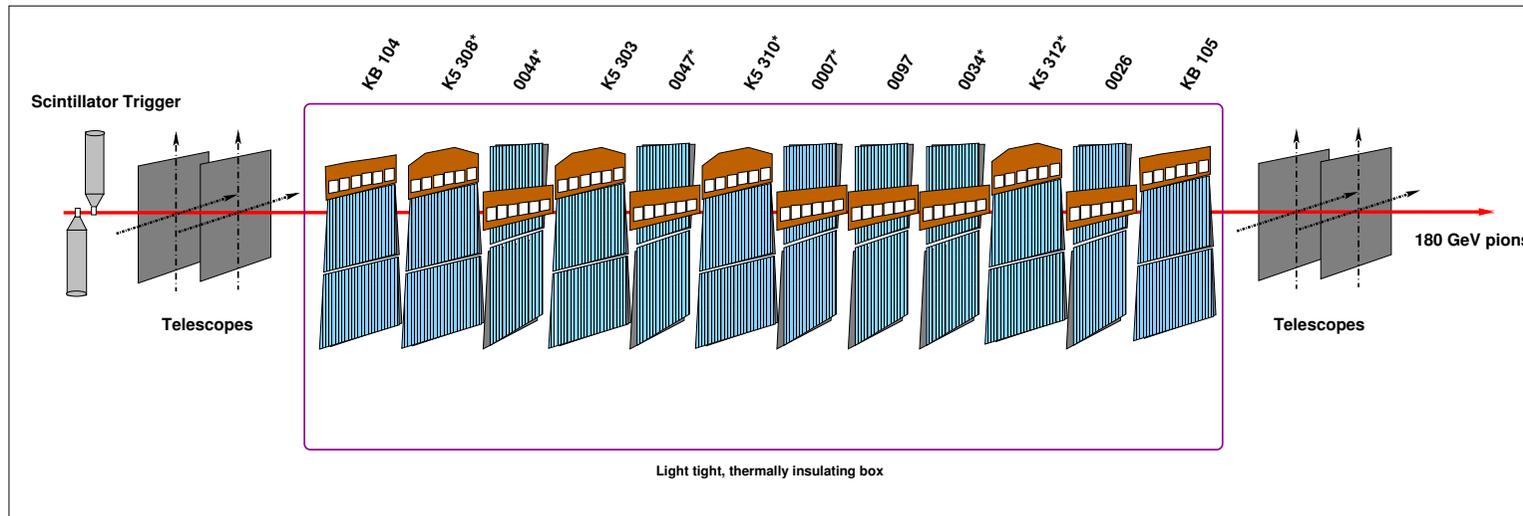


- Efficiency vs. timing of clock and trigger signal at 1 fC threshold. The width corresponds to 25 ns.
- Timing per chip vs. injected charge. The timewalk is defined as the maximum difference in timing at 1 fC threshold for 1.25 to 10 fC injected charges.
- The chips get slower after irradiation.  
Peaking time: 20 → 30 ns.
- The threshold will be crossed later after irradiation.  
Timewalk: 10 → more than 16 ns
- By increasing the Voltage for the analog part of the chip from 3.5 to 3.8 V, the timewalk can be brought within specifications for most of the channels.

**The chips get slower and the timewalk increases.**



# Tracking performance from test beam measurements



- Several fully irradiated modules, are placed at about the distances they will have in ATLAS.
- The tracking performance is studied, varying the noise occupancy via the threshold.
- The observed residuals of the space points per module are according to expectation from the geometry, about  $17\ (800)\ \mu m$  perpendicular (parallel) to the strips.
- For a track reconstructed from three modules, and at 1.2 fC threshold, an efficiency of more than 97% at about  $10^{-3}$  fake rate is achieved. For four modules the efficiency is still larger than 97%, however at lower fake rate, which is compatible with zero.

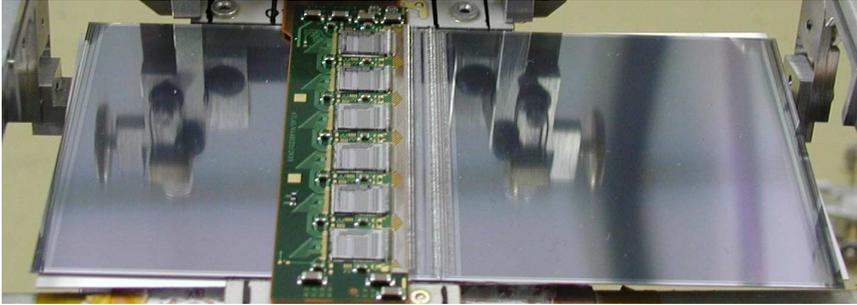
**The fully irradiated modules still allow for tracking with high efficiency and low fake rate.**



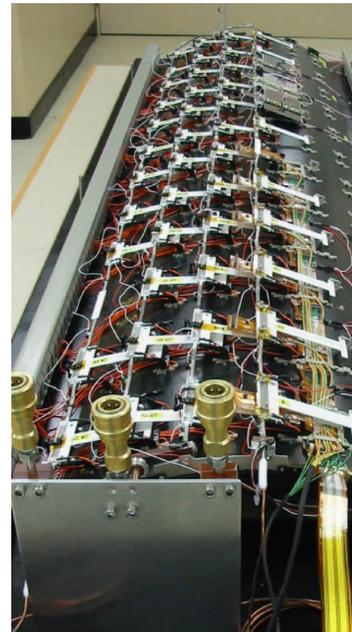
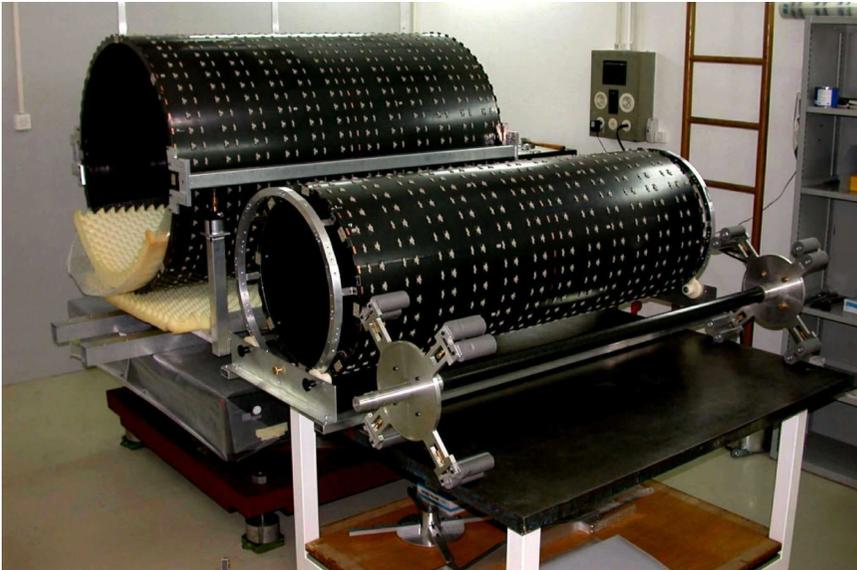
## Status of the production - the barrel part

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- Module production is distributed over the world. Production centers are at various institutes in Japan, Scandinavia, UK and the US. This means a complex logistics is needed.
- The module production is about 1/3 completed.

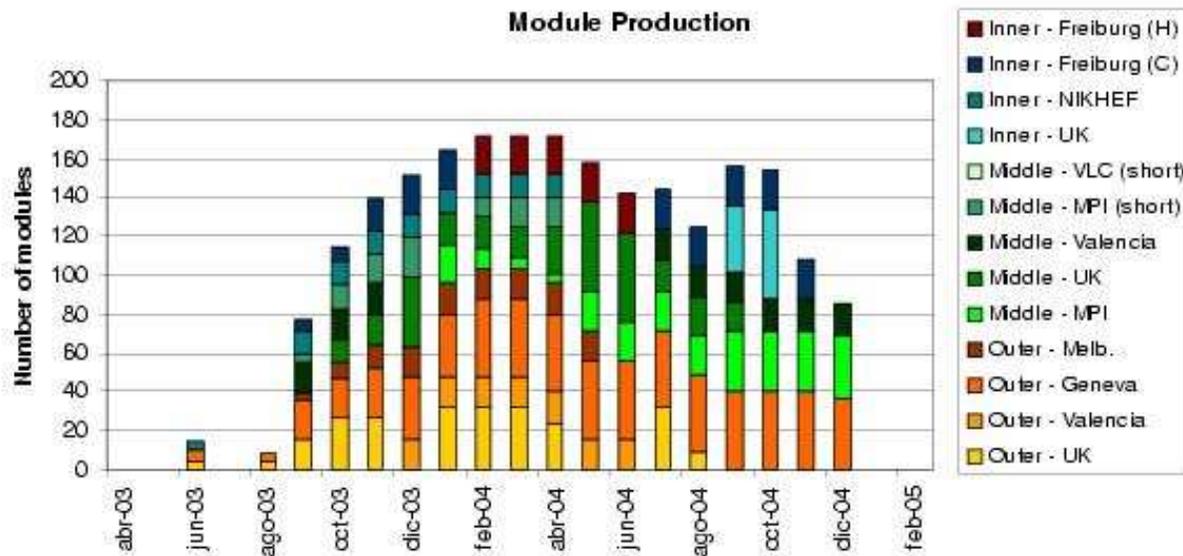


- Module to barrel mounting is done in the UK.
- Lots of services (cooling, cables, sensors for monitoring, . . .) have to be installed.

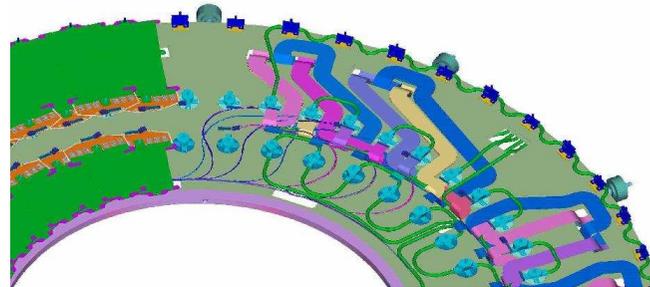
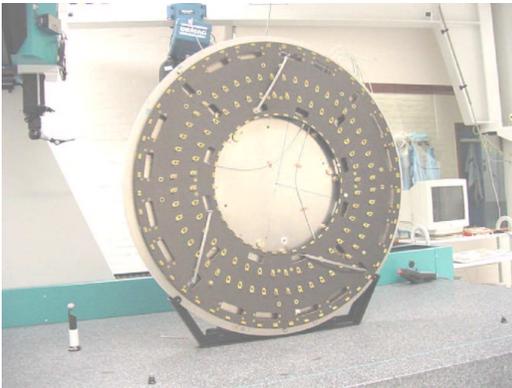
**There is still much work ahead.**



# Status of the production - the forward part



- The module production is distributed over various institutes in Europe and Australia. The existence of three different module types makes the logistics even more complex.
- Module production is about to start.



- Module to disk mounting is done at NIKHEF and Liverpool.
- Lots of services (cooling, cables, sensors for monitoring, . . .) have to be installed.

**The time schedule to complete the forward SCT is tight.**



## Conclusions ...

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- A part of the ATLAS inner detector will be equipped with silicon microstrip detectors, the SCT.
- A number of prototype forward modules demonstrate that the mechanical requirements can be met with sufficient yield.
- The electrical performance of non-irradiated modules is according to the design.
- The electrical performance of irradiated modules only allows for a marginal operating flexibility after receiving the full LHC dose, i.e. in the year 2017.
- The series production is underway for barrel modules and about to start for forward modules.

### ... and Outlook

- In december 2004 the barrel part is expected to be ready for integration.
- In may 2005 the forward part is expected to be ready for integration.